



New platform to realize “Autonomous Factory”

NPM-GH

Automation / Labor-saving Solution + Intelligent system solution to achieve manufacturing that is further in line with production plan

Key Features

Industry's top-class edge device

Latest evolution of NPM G Series

Remote operation option

Automatic recovery option

Autonomous control of variations in 5Ms



NPM-GH

<https://latam.connect.panasonic.com/pa/en/products/smart-factory-solutions/npm-gh>

PCB dimensions (mm)	Single-lane mode: L 50 mm × W50 mm ~ L 510 mm × W590 mmDual-lane mode: L 50 mm × W50 mm ~ L 510 mm × W 300 mm
PCB exchange	2.3 s (L 350 mm or less)5.0 s (L 350 mm or over to L 510 mm or less)
Electric Source	3-phase AC 200 , 220 , 380 , 400 , 420 , 480 V 2.1 kVA
Pneumatic Source	Min.0.5 MPa ~ Max. 0.8 MPa, 200 L / min (A.N.R.)
Dimension	W 975 mm × D 2 473 mm × H 1 444 mm
Mass	2 330 kg
Placement Head	FC16 headFC08 headFC03 head
Taping	FC16 head: Tape : 4 / 8 / 12 / 16 / 24 / 32 / 44 / 56 mmFC08 head: Tape : 4 ~ 56 / 72 mmFC03 head: Tape : 4 ~ 56 / 72 / 88 / 104 mm
Stick	FC08 head & FC03 head: ITF cart(17-slot) specifications : Max.48
Tray	FC08 head & FC03 head: Max.24
Placement Head max Speed	FC16 head: 51 500 cph (0.069 s / chip) high prod. / 37 500 cph (0.096 s / chip) high acc.FC08 head: 25 500 cph (0.141 s / chip) high prod. / 20 500 cph (0.176 s / chip): high acc.FC03 head: 10 100 cph (0.356 s / chip) high prod / 9 000 cph (0.4 s / chip) high acc.
Component dimensions	FC16 head: 0201 chip / 03015 chip ~ L 10 × W 10 × T 3FC08 head: 0402 chip ~ L 45 × W 45 or L 100 × W 40 × T 12FC03 head: 0603 chip ~ L 120 × W 90 or L 150 × W 25 × T 30
Placement Accuracy	FC16 head: ±25 µm /chip high prod / ±15 µm /chip high acc.FC08 head: ±25 µm / chip high prod / ±15 µm /chip high accFC03 head: ±25 µm / chip high prod / ±15 µm / chip high acc